

V _{CES}	600V
I _{C(100°C)}	30A
V _{CE(sat) (Typ.)}	1.4V
P _D	111W

Features

- 1) Low Collector Emitter Saturation Voltage
- 2) Soft Switching
- Built in Very Fast & Soft Recovery FRD (RFN - Series)
- 4) Pb free Lead Plating ; RoHS Compliant

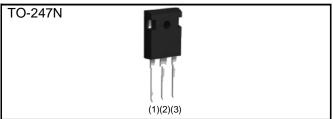
Applications

Partial Switching PFC

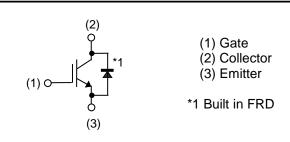
Discharge Circuit

Brake for Inverter

Outline



Inner Circuit



Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Tuno	Tape Width (mm)	-
Туре	Basic Ordering Unit (pcs)	450
	Taping Code	C11
	Marking	RGCL60TS60D

•Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	600	V
Gate - Emitter Voltage		V _{GES}	±30	V
Collector Oursent	$T_{\rm C} = 25^{\circ}{\rm C}$	Ι _C	48	А
Collector Current	T _C = 100°C	Ι _C	30	А
Pulsed Collector Current		I _{CP} *1	120	А
Diada Famulard Current	$T_{\rm C} = 25^{\circ}{\rm C}$	١ _F	35	А
Diode Forward Current	$T_{\rm C} = 100^{\circ}{\rm C}$	١ _F	20	А
Diode Pulsed Forward Current		I _{FP} ^{*1}	100	А
Dower Dissinction	$T_{\rm C} = 25^{\circ}{\rm C}$	P _D	111	W
Power Dissipation	T _C = 100°C	P _D	55	W
Operating Junction Temperature	-	T _j	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

*1 Pulse width limited by T_{jmax.}

Thermal Resistance

Parameter	Symbol	Values			Unit
Parameter		Min.	Тур.	Max.	Unit
Thermal Resistance IGBT Junction - Case	$R_{\theta(j\text{-}c)}$	-	-	1.34	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j\text{-}c)}$	-	-	2.28	°C/W

•IGBT Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector - Emitter Breakdown Voltage	BV _{CES}	I _C = 10μΑ, V _{GE} = 0V	600	-	-	V
Collector Cut - off Current	I _{CES}	V _{CE} = 600V, V _{GE} = 0V	-	-	10	μA
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30 V, V_{CE} = 0 V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	V _{GE(th)}	V _{CE} = 5V, I _C = 18.9mA	4.5	5.5	6.5	V
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$I_{C} = 30A, V_{GE} = 15V$ $T_{j} = 25^{\circ}C$ $T_{j} = 175^{\circ}C$	-	1.4 1.6	1.8 -	V

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•IGBT Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Deremeter	Currents et	Openalities					
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Input Capacitance	C _{ies}	V _{CE} = 30V	-	1600	-		
Output Capacitance	C _{oes}	$V_{GE} = 0V$	-	38	-	pF	
Reverse Transfer Capacitance	C _{res}	f = 1MHz	-	29	-		
Total Gate Charge	Q_g	V _{CE} = 300V	-	68	-		
Gate - Emitter Charge	Q_{ge}	I _C = 30A	-	13	-	nC	
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	27	-		
Turn - on Delay Time	t _{d(on)}	$I_{\rm C} = 30$ A, $V_{\rm CC} = 400$ V	-	44	-		
Rise Time	t _r	$V_{GE} = 15V, R_G = 10\Omega$	-	27	-	ns	
Turn - off Delay Time	$t_{d(off)}$	$T_j = 25^{\circ}C$	-	186	-		
Fall Time	t _f	Inductive Load	-	178	-		
Turn - on Switching Loss	E_{on}	*Eon includes diode	I	0.77	-	mJ	
Turn - off Switching Loss	E_{off}	reverse recovery	-	1.11	-	IIIJ	
Turn - on Delay Time	t _{d(on)}	$I_{\rm C} = 30$ A, $V_{\rm CC} = 400$ V	-	40	-		
Rise Time	t _r	$V_{GE} = 15V, R_G = 10\Omega$	-	45	-	nc	
Turn - off Delay Time	$t_{d(off)}$	T _j = 175°C	-	207	-	ns	
Fall Time	t _f	Inductive Load	-	272	-		
Turn - on Switching Loss	Eon	*Eon includes diode	-	0.97	-	~ I	
Turn - off Switching Loss	E_{off}	reverse recovery	-	1.54	-	mJ	
		$I_{\rm C} = 120$ A, $V_{\rm CC} = 480$ V			-		
Reverse Bias Safe Operating Area	RBSOA	$V_{P} = 600V, V_{GE} = 15V$	FU	LL SQUA	RE	-	
		$R_{G} = 60\Omega, T_{j} = 175^{\circ}C$					

•FRD Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Onit	
		I _F = 20A					
Diode Forward Voltage	V_{F}	$T_j = 25^{\circ}C$	-	1.45	1.9	V	
		T _j = 175°C	-	1.25	-		
Diode Reverse Recovery Time	t _{rr}		-	58	-	ns	
Diode Peak Reverse Recovery Current	I _{rr}	I _F = 20A V _{CC} = 400V	-	6.3	-	A	
Diode Reverse Recovery Charge	Q _{rr}	di _F /dt = 200A/µs T _j = 25°C	-	0.20	-	μC	
Diode Reverse Recovery Energy	Err		-	7.4	-	μJ	
Diode Reverse Recovery Time	t _{rr}		-	256	-	ns	
Diode Peak Reverse Recovery Current	I _{rr}	$I_F = 20A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	10.4	-	A	
Diode Reverse Recovery Charge	Q _{rr}		-	1.35	-	μC	
Diode Reverse Recovery Energy	Err		-	146.5	-	μJ	

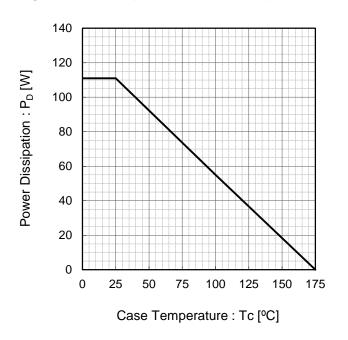


Fig.1 Power Dissipation vs. Case Temperature

Fig.2 Collector Current vs. Case Temperature

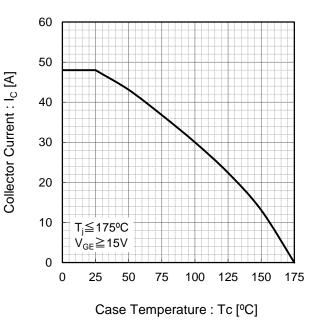
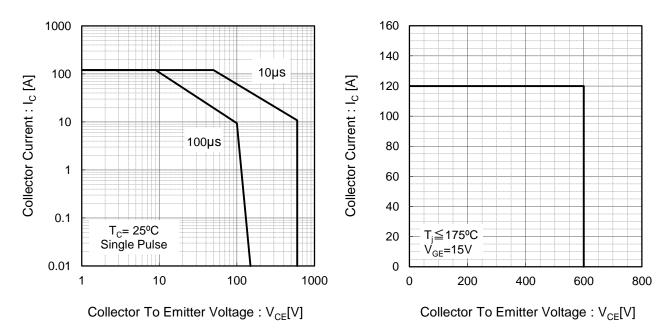


Fig.3 Forward Bias Safe Operating Area

Fig.4 Reverse Bias Safe Operating Area



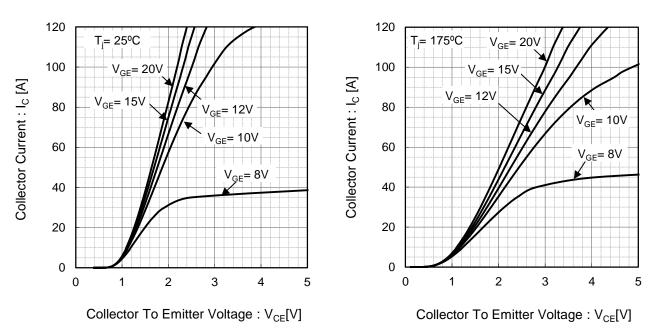
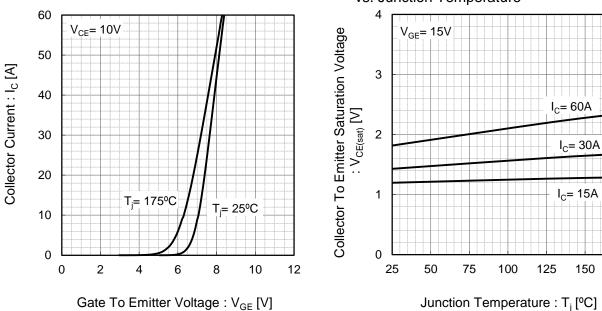


Fig.5 Typical Output Characteristics

Fig.7 Typical Transfer Characteristics

Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature

Fig.6 Typical Output Characteristics



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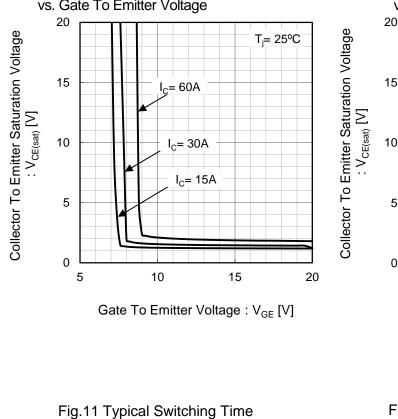


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

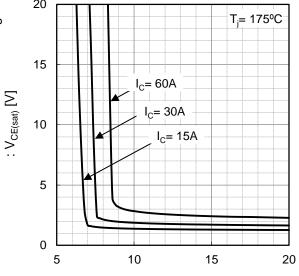


Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

Gate To Emitter Voltage : V_{GE} [V]

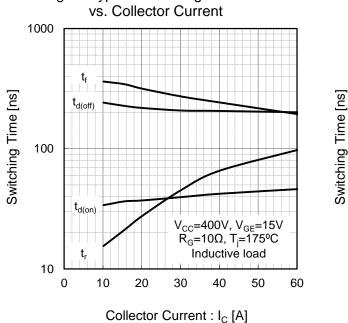
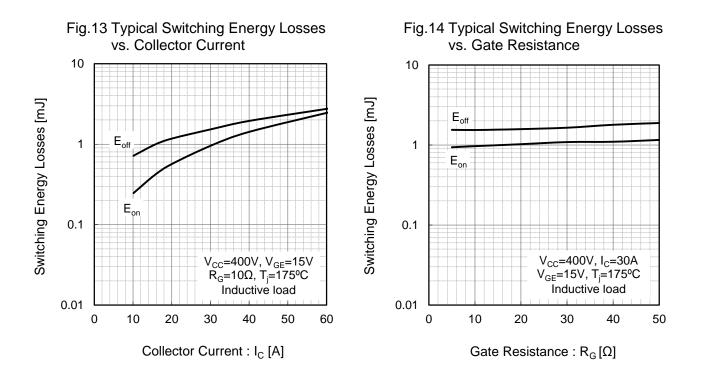
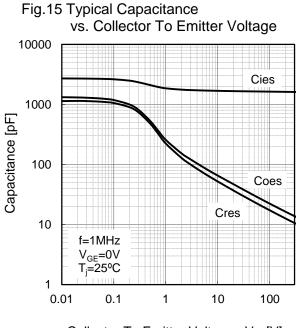


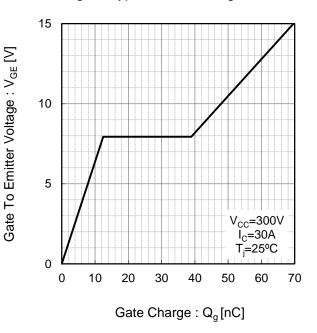
Fig.12 Typical Switching Time vs. Gate Resistance





Collector To Emitter Voltage : V_{CE}[V]

Fig.16 Typical Gate Charge



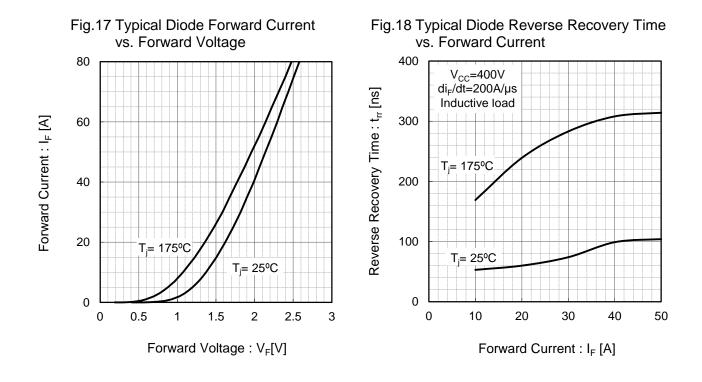


Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

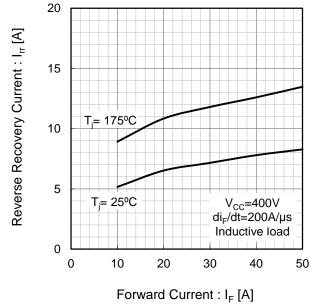
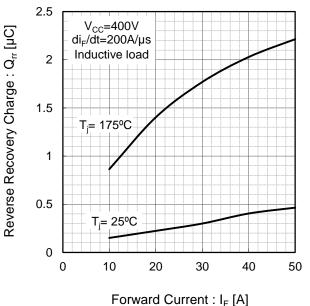


Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current



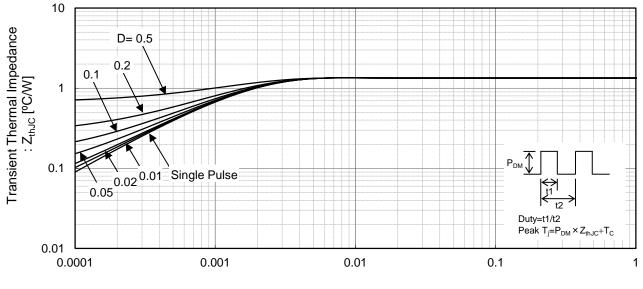
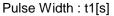


Fig.21 IGBT Transient Thermal Impedance



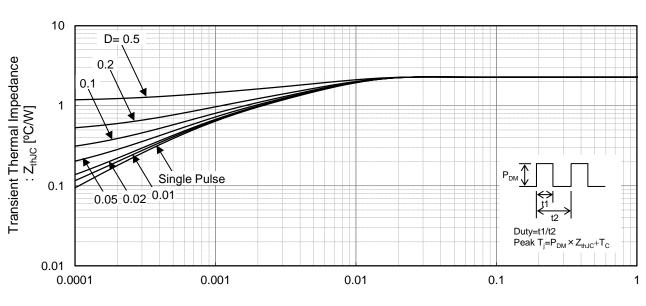


Fig.22 Diode Transient Thermal Impedance

Pulse Width : t1[s]

●Inductive Load Switching Circuit and Waveform

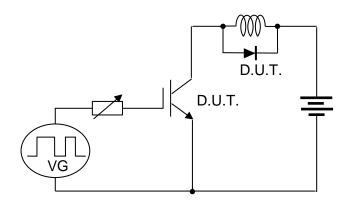


Fig.23 Inductive Load Circuit

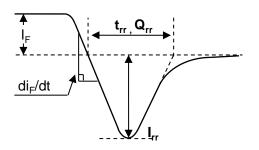


Fig.25 Diode Reverce Recovery Waveform

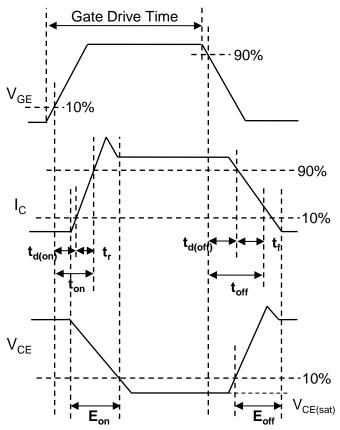


Fig.24 Inductive Load Waveform

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